SiJ458DP

Vishay Siliconix



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	1 - 1						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V, } I_D = 250 \mu\text{A}$	30			٧	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			32		1.1/0.1	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 6.7		mV/°	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.0		2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C			10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α	
	R _{DS(on)}	V _{GS} = 10 V, I _D = 20 A		0.0018	0.0022	Ω	
Drain-Source On-State Resistance ^a		$V_{GS} = 4.5 \text{ V}, I_D = 15 \text{ A}$		0.0021	0.0026		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 10 V, I _D = 20 A		100		S	
Dynamic ^b	<u> </u>				l		
Input Capacitance	C _{iss}			4810			
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		892		pF	
Reverse Transfer Capacitance	C _{rss}			444			
		V _{DS} = 15 V, V _{GS} = 10 V, I _D = 20 A		81	122		
Total Gate Charge	Q_g			40.6	61	_	_
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}$		10.8		nC	
Gate-Drain Charge	Q_{gd}			13.5			
Gate Resistance	R_{g}			2.2	Ω		
Turn-On Delay Time	t _{d(on)}			16	30		
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		10	20		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 10 A, V_{GEN} = 10 V, R_g = 1 Ω		43	30 20 80 18		
Fall Time	t _f			9	18	1	
Turn-On Delay Time	t _{d(on)}			38	75	ns	
Rise Time	t _r	V_{DD} = 15 V, R_L = 1.5 Ω		44	80	1	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 10 A, V_{GEN} = 4.5 V, R_g = 1 Ω		49	90	1	
Fall Time	t _f	24		24	45	1	
Drain-Source Body Diode Characteristic	cs				l		
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			60	_	
Pulse Diode Forward Current ^a	I _{SM}				80	A	
Body Diode Voltage	V _{SD}	I _S = 4 A		0.7	1.1	V	
Body Diode Reverse Recovery Time	t _{rr}			35	70	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	32		32	64	nC	
Reverse Recovery Fall Time	t _a	I _F = 10 A, dl/dt = 100 A/μs, T _J = 25 °C			1		
Reverse Recovery Rise Time	t _b			18		ns	

Notes:

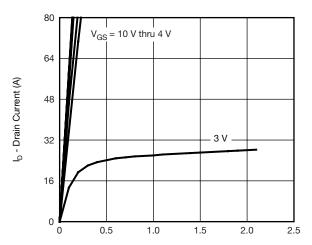
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



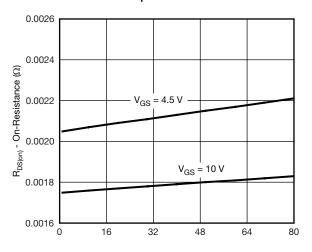
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



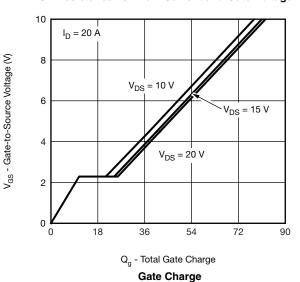
 $V_{\rm DS}$ - Drain-to-Source Voltage (V)

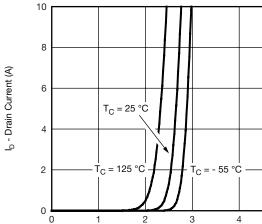
Output Characteristics



I_D - Drain Current (A)

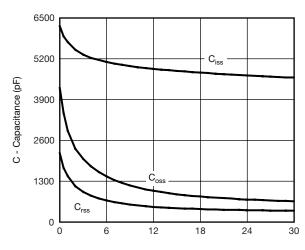
On-Resistance vs. Drain Current and Gate Voltage





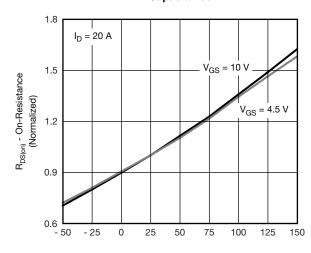
V_{GS} - Gate-to-Source Voltage (V)

Transfer Characteristics



 $\rm V_{\rm DS}$ - Drain-to-Source Voltage (V)

Capacitance



T_J - Junction Temperature (°C)

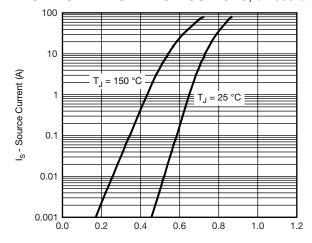
On-Resistance vs. Junction Temperature

SiJ458DP

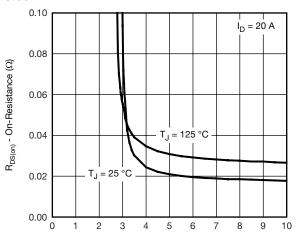
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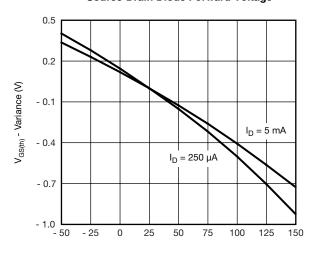
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

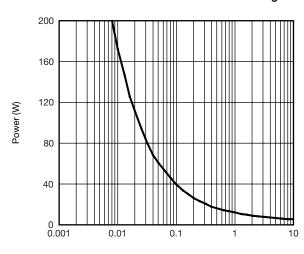


V_{SD} - Source-to-Drain Voltage (V) **Source-Drain Diode Forward Voltage**

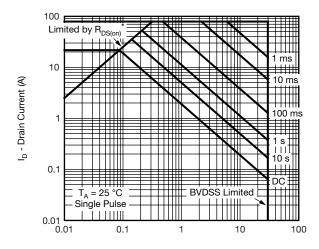




 T_J - Junction Temperature (°C) **Threshold Voltage**



Time (s)
Single Pulse Power, Junction-to-Ambient

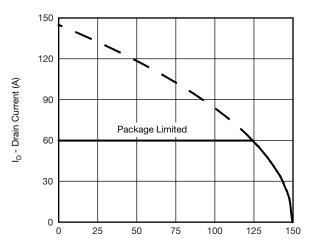


 $\begin{aligned} &V_{DS}\text{ - Drain-to-Source Voltage (V)}\\ *V_{GS}>&\min \text{minimum }V_{GS}\text{ at which }R_{DS(on)}\text{ is specified}\\ &\textbf{Safe Operating Area, Junction-to-Ambient}\end{aligned}$



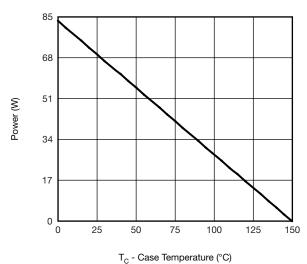
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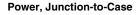
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

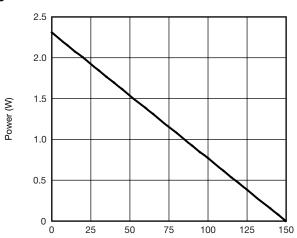


T_C - Case Temperature (°C)

Current Derating*







 $\rm T_A$ - Ambient Temperature (°C)

Power, Junction-to-Ambient

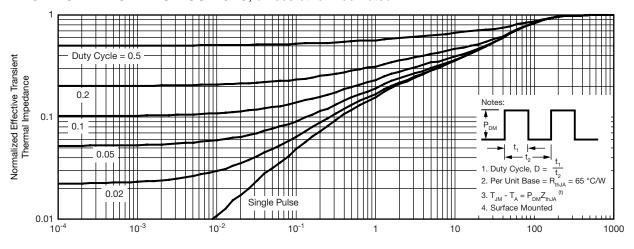
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

SiJ458DP

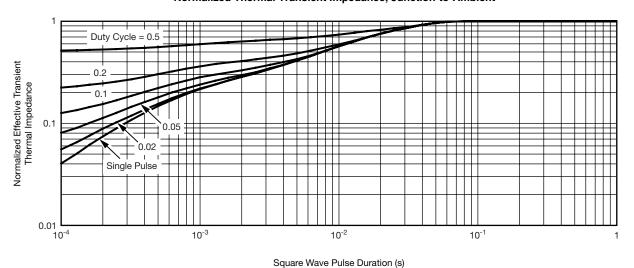
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Square Wave Pulse Duration (s) Normalized Thermal Transient Impedance, Junction-to-Ambient

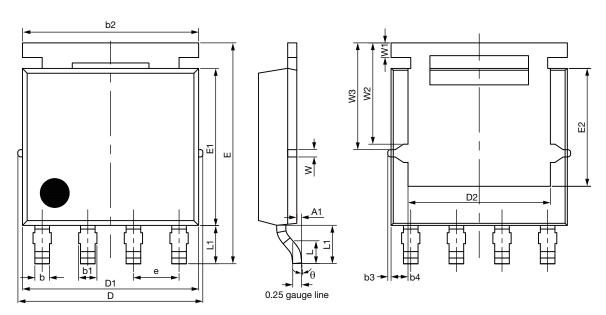


Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data,see www.vishay.com/ppg?65709.

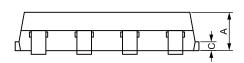
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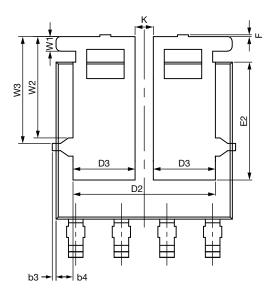
PowerPAK® SO-8L Case Outline for Non-Al Parts





Backside view (single)





Backside view (dual)

Revision: 16-May-16 1 Document Number: 69003





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DIM		MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX		
Α	1.00	1.07	1.14	0.039	0.042	0.045		
A1	0.00	-	0.127	0.00	-	0.005		
b	0.33	0.41	0.48	0.013	0.016	0.019		
b1	0.44	0.51	0.58	0.017	0.020	0.023		
b2	4.80	4.90	5.00	0.189	0.193	0.197		
b3	0.094			0.004				
b4	0.47			0.019				
С	0.20	0.25	0.30	0.008	0.010	0.012		
D	5.00	5.13	5.25	0.197	0.202	0.207		
D1	4.80	4.90	5.00	0.189	0.193	0.197		
D2	3.86	3.96	4.06	0.152	0.156	0.160		
D3	1.63	1.73	1.83	0.064	0.068	0.072		
е	1.27 BSC			0.050 BSC				
E	6.05	6.15	6.25	0.238	0.242	0.246		
E1	4.27	4.37	4.47	0.168	0.172	0.176		
E2	3.18	3.28	3.38	0.125	0.129	0.133		
F	-	-	0.15	-	-	0.006		
L	0.62	0.72	0.82	0.024	0.028	0.032		
L1	0.92	1.07	1.22	0.036	0.042	0.048		
K	0.51			0.020				
W	0.23			0.009				
W1	0.41			0.016				
W2	2.82			0.111				
W3	2.96			0.117				
θ	0°	-	10°	0°	-	10°		

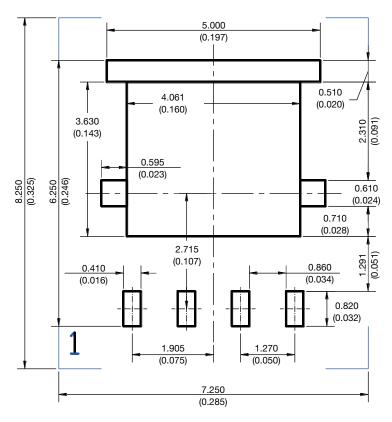
DWG: 5976

Note

• Millimeters will gover



RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)

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